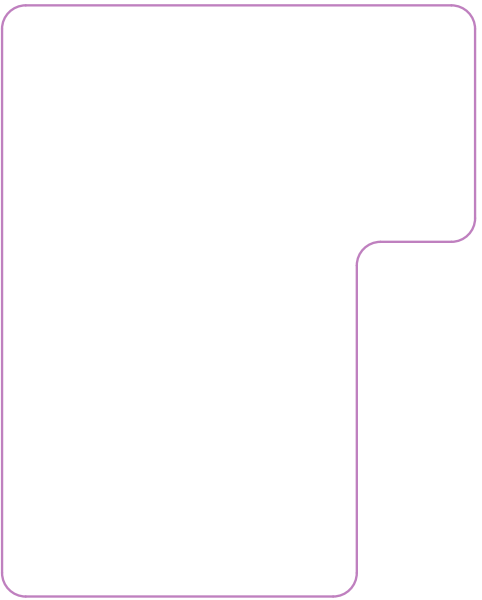
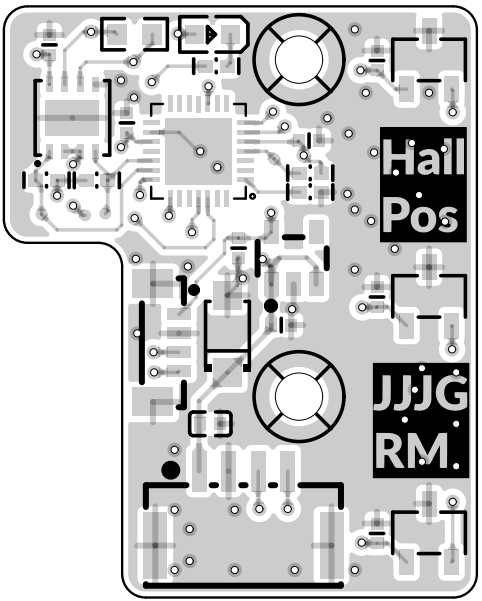
NC1
LED1
SCREW2
C6
R1
C5
U4
U6
C2
U3
C1
TP1
R3
R4
R5
R2
TP2
TP3
TP4
C8
U7
U2
C3
CN1
D1
C7
SCREW1
C9
U5
C4
U1



No.	Quantity	Comment	Designator	Footprint	Value	Manufacturer
1	6	100nF	C1,C2,C3,C4,C5,C6	C0402-YWT_1	100nF	SAMSUNG( )
2	2	1uF	C7,C8	C0402-YWT_1	1uF	SAMSUNG( )
3	1	4.7uF	C9	C0402	4.7uF	HRE(¯ð)
4	1	WAFER-0.8-4PLB	CN1	CONN-SMD_4P-P0.80_XUNPU_WAFER-0.8-4PLB		XUNPU(¯n)
5	1	SMF5.0A	D1	SOD-123FL_L2.7-W1.8-LS3.8-RD		R+O(• Ú)
6	1	KT-0603R	LED1	LED0603-RD		KENTO
7	1	120©	NC1	R0603	120©	FOJAN(ìw)
8	3	5.1k©	R1,R4,R5	R0402-YWT_1	5.1k©	UNI-ROYAL(š) Tj T* (ð)
9	2	10k©	R2,R3	R0402-YWT_1	10k©	UNI-ROYAL(š) Tj T* (ð)
10	2	M2º	SCREW1,SCREW2	M2º		
11	4	Test-Point	TP1,TP2,TP3,TP4	Test-Point-0.5mm		
12	3	SC4703SO-TR	U1,U2,U4	SOT-23-3_L2.9-W1.6-P1.90-LS2.8-BR		Semiment([S) Tj T* ()
13	1	GD32E230G6U6TR	U3	QFN-28_L4.0-W4.0-P0.40-BL-EP2.8		GigaDevice() Tj T* (F °)
14	1	WAFER-GH1.25-4PWB	U5	CONN-SMD_4P-P1.25_XUNPU_WAFER-GH1.25-4PWB		XUNPU(¯n)
15	1	SIT3088ETK	U6	DFN-8_L3.0-W3.0-P0.65-BL-EP		SIT(¯›y)
16	1	XC6210B332MR	U7	SOT-23-5_L2.9-W1.6-P0.95-LS2.8-BR		TECH PUBLIC(ð)


Hall
Pos
JJJG
RM.


机甲大师
ROBOMASTER
JG
冀甲精工
JIJIAJINGGONG

